Abstract

A resin supply device according to the present invention is a resin supply device configured to supply a resin material to a molding die that molds a resin on a substrate by compression molding, the resin supply device including: a first tray on which a resin material is placed; at least one second tray that is smaller than the first tray and on which the resin material is placed; a tray conveyance unit that conveys the second tray onto the first tray; a resin supply unit that supplies the resin material to the second tray; and a control unit, in which the control unit executes a first step of spreading the resin material on the second tray by the resin supply unit; a second step of spreading the resin material so as to overlap an outer edge of the resin material spread in the first step by the resin supply unit; and a third step of conveying the second tray to the first tray and placing the resin material on the second tray in a region of the first tray where the resin material is not placed, and the resin material is placed in the first tray by repeating the first to third steps.

Fig. 10E